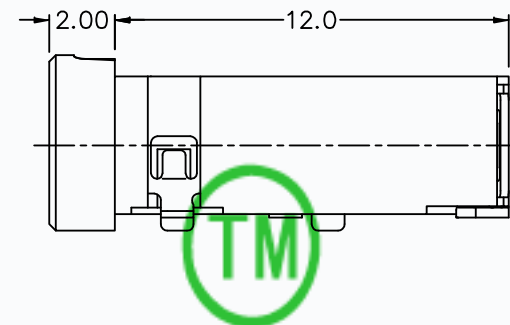
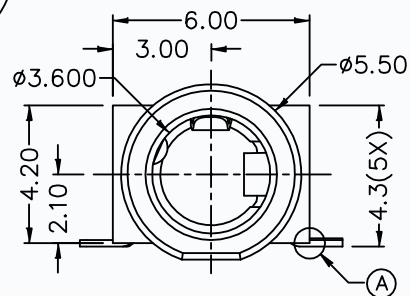
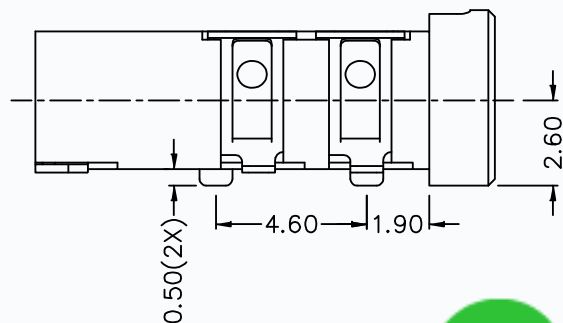
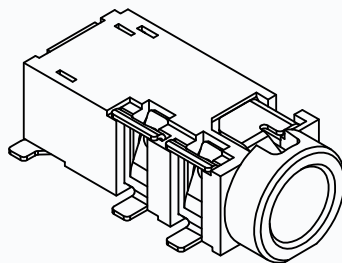


CAD FILE:



CMTDDZ

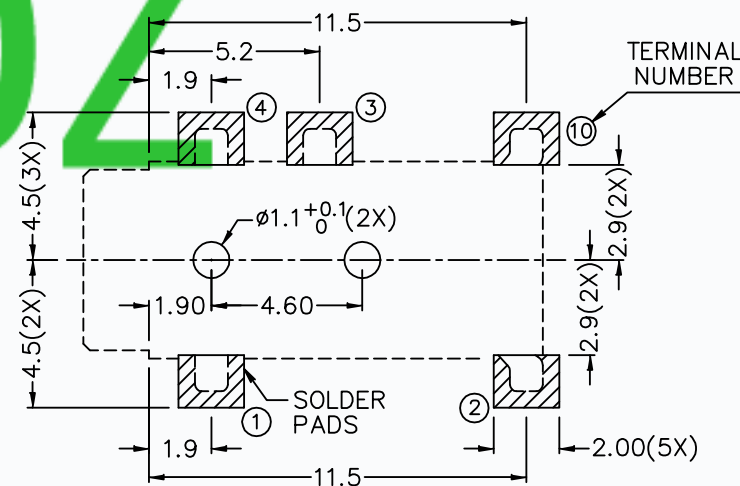


A DETAIL COPLANARITY

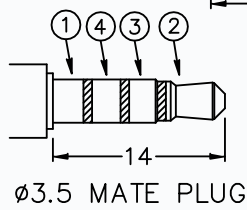
* MATERIAL

TERMINAL 1 : COPPER ALLOY
 TERMINAL 2 : COPPER ALLOY
 TERMINAL 3 : COPPER ALLOY
 TERMINAL 4 : COPPER ALLOY
 TERMINAL 10 : COPPER ALLOY
 HOUSING : PA6T

MODEL NO.	T13-3536D
SCHEMATIC	



RECOMMENDED
SOLDER PAD LAYOUT
(TOP VIEW)



Ø3.5 MATE PLUG

TOLERANCE
 UNLESS SPECIFIED
 WITHIN 1.5mm : ±0.1mm
 OVER 1.5mm : ±0.2mm

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 DONGGUAN TIANDU ELECTRONICS CO., LTD.

TITLE : 3.5mm SMD PHONE JACK

UNIT : mm

DRWG NO.: CMTDDZ-T13-3526-00

MODEL: T13-3536D

SCALE: 3:1

DWN. ERIC 2013-6-17

CMTDDZ 东莞市田都电子有限公司
 DONGGUAN TIANDU ELECTRONICS CO.,LTD.

CHK'D MAIKO 2013-6-17

APPD. Coco 2013-6-17

APPD. DESCRIPTIONS OF REVISION